IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Serial No.: 10/550,829

Filing Date: Sept. 23, 2005

Applicant(s): Mahlkow et al.

For: Solution for Etching

Copper Surfaces and Method of Depositing Metal on

Copper Surfaces

Examiner: Roberts P. Culbert

Art Unit: 1763

Attorney

Docket No.: 295-05

Confirm. No.: 1743

Commissioner for Patents P.O. Box 1450

Alexandria, VA 22313-1450

above-identified application as follows:

Sir:

In response to the Final Office Action of October 26, 2007, please amend the

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

AMENDMENT

Remarks/Arguments begin on page 6 of this paper.

This submission is timely filed on or prior to January 26, 2007. A Request for Continued Examination accompanies this submission, as well as the associated fee of \$810.00. In the event that an additional fee is required with respect to this communication, the Commissioner is hereby authorized to charge any additional fees, or credit any overpayment, to Paul & Paul Denosit Account No.16-0750.

CERTIFICATE OF TRANSMISSION

I hereby certify that this correspondence is being transmitted to the U.S. Patent and Trademark Office via the EFS-Web electronic filing system

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